

# P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY							
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$		Q <sub>g</sub> (Typ.)				
- 30	0.056at V <sub>GS</sub> = - 10 V	- 20	19 nC				
- 30	0.072 at V <sub>GS</sub> = -4.5 V	- 15	19110				

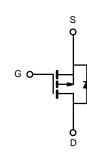
# **FEATURES**

- Halogen-free
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> Tested
- 100 % UIS Tested



### **APPLICATIONS**

- Load Switch
- · Notebook Adaptor Switch



P-Channel MOSFET

TO-25	51	
_~_	$^{\sim}$	
0		
		Drain Connected to Drain-Tab
G D	S	
Top Vi	ew	

ABSOLUTE MAXIMUM RATINGS $T_{A}$	= 25 °C, unless other	erwise noted			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	$V_{DS}$	- 30	V		
Gate-Source Voltage	$V_{GS}$	± 20			
	T <sub>C</sub> = 25 °C		- 20		
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>C</sub> = 70 °C	] [	- 15		
Continuous Drain Current (1) = 130 C)	T <sub>A</sub> = 25 °C	l o	-7.9 <sup>a, b</sup>		
	T <sub>A</sub> = 70 °C	1	- 5.6 <sup>a, b</sup>	^	
Pulsed Drain Current	I <sub>DM</sub>	- 60	Α		
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	1-	- 20		
Continuous Source-Dialii Diode Current	T <sub>A</sub> = 25 °C	ls l	- 7.9 <sup>a, b</sup>		
Avalanche Current		I <sub>AS</sub>	- 20		
Single-Pulse Avalanche Energy  L = 0.1 mH		E <sub>AS</sub>	20	mJ	
	T <sub>C</sub> = 25 °C		20		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	$P_{D}$	15	w	
Maximum Fower Dissipation	T <sub>A</sub> = 25 °C	' D	2.7 <sup>a, b</sup>	VV	
	T <sub>A</sub> = 70 °C		1.7 <sup>a, b</sup>		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter			Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a, c</sup>	t ≤ 10 s	R <sub>thJA</sub>	38	46	°C/W	
Maximum Junction-to-Foot	Steady State	R <sub>thJF</sub>	20	25	C/VV	

#### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W. d. Based on  $T_C$  = 25 °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V	
V <sub>DS</sub> Temperature Coefficient	$V_{\rm DS}$ Temperature Coefficient $\Delta V_{\rm DS}/T_{\rm J}$			- 34		mV.	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μA		5.3		°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 1.4		- 2.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 100	nA	
Zoro Coto Valtorio Droin Current	1	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$			- 1	—— иА	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 5		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 20			Α	
	_	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 6 A	0.056			Ω	
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 4 A		0.072			
Forward Transconductancea	9 <sub>fs</sub>	V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 6 A		28		S	
Dynamic <sup>b</sup>	-					<u>l</u>	
Input Capacitance				1150			
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = - 15 V, V <sub>GS</sub> = 0 V, f = 1 MHz		205		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			140			
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = - 15 V, V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 6 A		27	43		
				19	25		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -6 \text{ A}$		6		nC	
Gate-Drain Charge	Q <sub>qd</sub>			12			
Gate Resistance	R <sub>g</sub>	f = 1 MHz		2.2	4.4	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			13	25		
Rise Time	t <sub>r</sub>	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		12	24		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong -10 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		40	70		
Fall Time	t <sub>f</sub>			9	18		
Turn-On Delay Time	t <sub>d(on)</sub>			48	80	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		92	160		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong -6$ A, $V_{GEN} = -4.5$ V, $R_a = 1$ $\Omega$		34	60		
Fall Time	t <sub>f</sub>			19	35		
Drain-Source Body Diode Characteris	stics						
Continous Source-Drain Diode Current I <sub>S</sub>		T <sub>C</sub> = 25 °C			- 4.1		
Pulse Diode Forward Current	I <sub>SM</sub>				- 60	Α	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = -3 A, V <sub>GS</sub> = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>	5 . 55		27	45	ns	
Body Diode Reverse Recovery Charge Q <sub>rr</sub>		1		16	27	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		12			
Reverse Recovery Rise Time	t <sub>b</sub>	┥		15		ns	

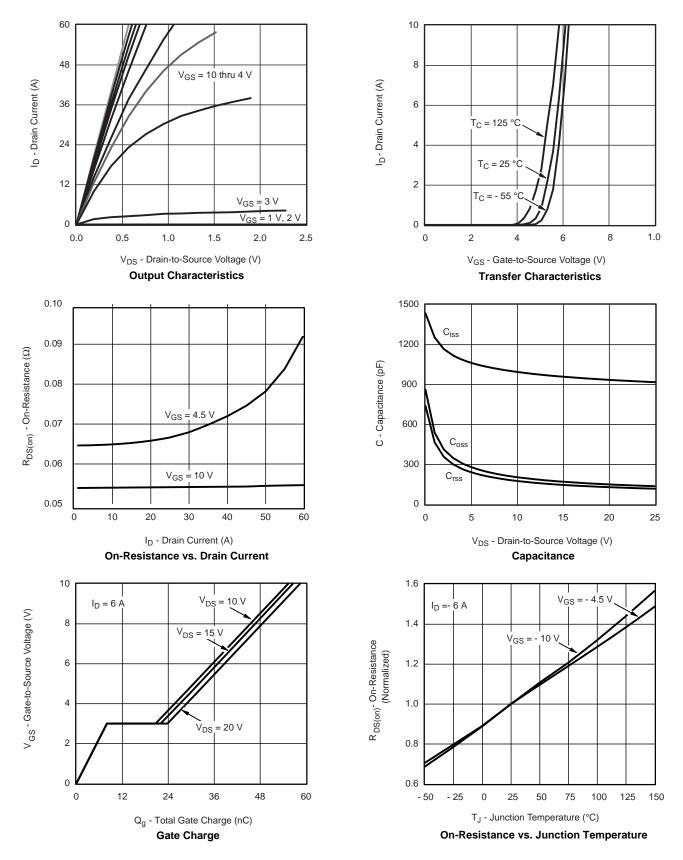
### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

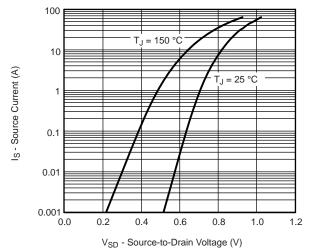


## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

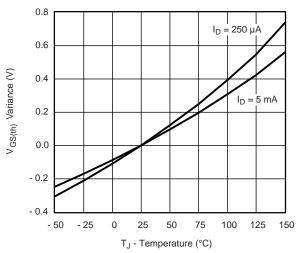




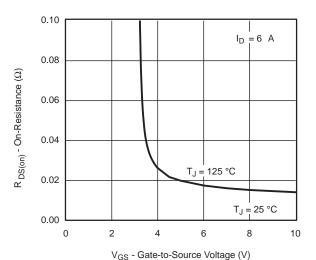
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



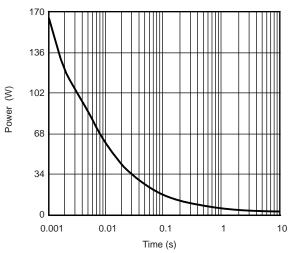
Source-Drain Diode Forward Voltage



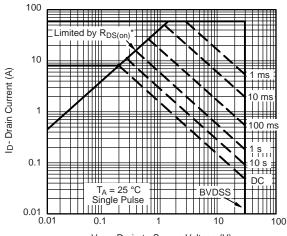
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

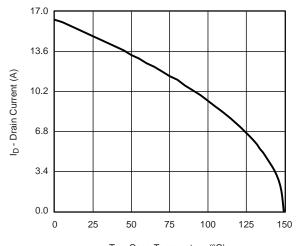


 $V_{DS}$  - Drain-to-Source Voltage (V) \*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area

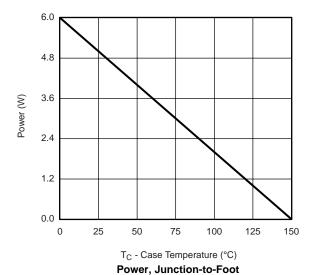


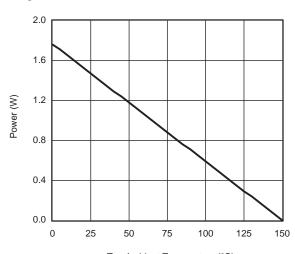
## MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



 $T_{\mbox{\scriptsize C}}$  - Case Temperature (°C)

## Current Derating\*



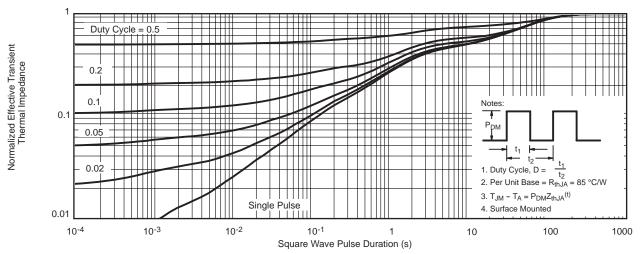


 $\label{eq:TA-Ambient Temperature (°C)}$  Power Derating, Junction-to-Ambient

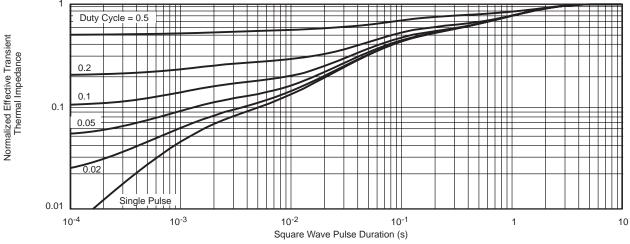
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



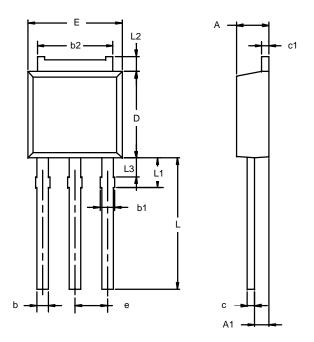
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



## TO-251AA



	MILLIM	IETERS	INCHES		
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
E	6.48	6.73	0.255	0.265	
е	2.28	BSC	0.090	BSC	
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	



# **Disclaimer**

All products due to improve reliability, function or design or for other reasons, product specifications and data are subject to change without notice.

Taiwan VBsemi Electronics Co., Ltd., branches, agents, employees, and all persons acting on its or their representatives (collectively, the "Taiwan VBsemi"), assumes no responsibility for any errors, inaccuracies or incomplete data contained in the table or any other any disclosure of any information related to the product.(www.VBsemi.com)

Taiwan VBsemi makes no guarantee, representation or warranty on the product for any particular purpose of any goods or continuous production. To the maximum extent permitted by applicable law on Taiwan VBsemi relinquished: (1) any application and all liability arising out of or use of any products; (2) any and all liability, including but not limited to special, consequential damages or incidental; (3) any and all implied warranties, including a particular purpose, non-infringement and merchantability guarantee.

Statement on certain types of applications are based on knowledge of the product is often used in a typical application of the general product VBsemi Taiwan demand that the Taiwan VBsemi of. Statement on whether the product is suitable for a particular application is non-binding. It is the customer's responsibility to verify specific product features in the products described in the specification is appropriate for use in a particular application. Parameter data sheets and technical specifications can be provided may vary depending on the application and performance over time. All operating parameters, including typical parameters must be made by customer's technical experts validated for each customer application. Product specifications do not expand or modify Taiwan VBsemi purchasing terms and conditions, including but not limited to warranty herein.

Unless expressly stated in writing, Taiwan VBsemi products are not intended for use in medical, life saving, or life sustaining applications or any other application. Wherein VBsemi product failure could lead to personal injury or death, use or sale of products used in Taiwan VBsemi such applications using client did not express their own risk. Contact your authorized Taiwan VBsemi people who are related to product design applications and other terms and conditions in writing.

The information provided in this document and the company's products without a license, express or implied, by estoppel or otherwise, to any intellectual property rights granted to the VBsemi act or document. Product names and trademarks referred to herein are trademarks of their respective representatives will be all.

## **Material Category Policy**

Taiwan VBsemi Electronics Co., Ltd., hereby certify that all of the products are determined to be RoHS compliant and meets the definition of restrictions under Directive of the European Parliament 2011/65 / EU, 2011 Nian. 6. 8 Ri Yue restrict the use of certain hazardous substances in electrical and electronic equipment (EEE) - modification, unless otherwise specified as inconsistent.(www.VBsemi.com)

Please note that some documents may still refer to Taiwan VBsemi RoHS Directive 2002/95 / EC. We confirm that all products identified as consistent with the Directive 2002/95 / EC European Directive 2011/65 /.

Taiwan VBsemi Electronics Co., Ltd. hereby certify that all of its products comply identified as halogen-free halogen-free standards required by the JEDEC JS709A. Please note that some Taiwanese VBsemi documents still refer to the definition of IEC 61249-2-21, and we are sure that all products conform to confirm compliance with IEC 61249-2-21 standard level JS709A.

## **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by VBsemi Elec manufacturer:

Other Similar products are found below:

614233C 648584F NTNS3A92PZT5G IRFD120 IRFF430 JANTX2N5237 2N7000 2SK2464-TL-E FCA20N60\_F109 FDZ595PZ 2SJ277-DL-E 2SK2267(Q) 2SK2545(Q,T) 405094E 423220D MCH6646-TL-E MIC4420CM-TR VN1206L 614234A 715780A

SSM6J414TU,LF(T 751625C PSMN4R2-30MLD TK31J60W5,S1VQ(O 2SK2614(TE16L1,Q) DMN1017UCP3-7 EFC2J004NUZTDG

FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE2384 NTE2969 NTE6400A DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 SSM6P54TU,LF DMP22D4UFO-7B IPS60R3K4CEAKMA1 DMN1006UCA6-7 DMN16M9UCA6-7 STF5N65M6 STU5N65M6

C3M0021120D DMN13M9UCA6-7 BSS340NWH6327XTSA1 MCM3400A-TP DMTH10H4M6SPS-13 IPS60R1K0PFD7SAKMA1

IPS60R360PFD7SAKMA1